

Examiner's Copy

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TI Lead-free **tin-base solder** pastes for chip
bonding
IN Kato, Rikiya; Munakata, Osamu; Toyota, Yoshitaka
PA Senju Metal Industry Co., Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 7 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
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PI	JP 2001058286	A2	20010306	JP 1999-234345	19990820
AB	The Sn-base solder pastes contain 0.2-1.0 wt.% Ag . The pastes may also contain Sb and/or Cu at .ltoreq.1.0 wt.% or Ni, Co, Fe, Mn, Cr, and/or Mo at .ltoreq.0.3 wt.% as strengthening elements, Bi, In, and/or Zn at 0.5-3.0 wt.% as m. p .-lowering elements, and/or P , Ga, and/or Ge at .ltoreq.0.2 wt.% as antioxidant elements. The solder pastes prevent rising of electronic chips during bonding them onto printed circuit boards, etc.				